



Material Content Data Sheet



Halogen-Free

Sales Product Name	ESD108-B1-CSP0201 E6327	Issued	24. February 2022
MA#	MA005700206		
Package	SG-WLL-2-1	Weight*	0.07 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.063	93.83	93.83	938269	938269
pad	inorganic material	silicon	7440-21-3	0.000			15	
	non noble metal	copper	7440-50-8	0.000			30	
	inorganic material	phosphorus	7723-14-0	0.000	0.08		850	
	non noble metal	aluminium	7429-90-5	0.000	0.34		3415	
	noble metal	palladium	7440-05-3	0.000	0.56		5578	
	noble metal	gold	7440-57-5	0.001	0.90		8979	
	non noble metal	nickel	7440-02-0	0.003	4.10	5.98	40955	59822
passivation	inorganic material	silicon dioxide	60676-86-0	0.000	0.07		686	
	inorganic material	silicon nitride	12033-89-5	0.000	0.12	0.19	1223	1909
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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